



# SOT1887-1

wafer level chip-scale package; 48 bumps; 3.72 mm x 2.79 mm x 0.525 mm (Backside coating included)

7 October 2016

Package information

## 1. Package summary

<b>Dimensions (mm)</b>	3.72 x 2.79 x 0.525
<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP48
<b>Package outline version code</b>	SOT1887-1
<b>Manufacturer package code</b>	SOT1887
<b>Package type industry code</b>	WLCSP
<b>Package outline version description</b>	wafer level chip-scale package; 48 bumps; 3.72 mm x 2.79 mm x 0.525 mm (Backside coating included)
<b>Package style descriptive code</b>	WLCSP
<b>Package body material type</b>	X
<b>Mounting method type</b>	S (surface mount)
<b>Package life cycle status</b>	REL
<b>Security status</b>	COMPANY PUBLIC
<b>Issue date</b>	4-10-2016
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A <sub>2</sub>	package height	0.3	-	0.325	0.35	mm
A	seated height	0.485	-	0.525	0.565	mm
D	package length	3.69	-	3.72	3.75	mm
E	package width	2.76	-	2.79	2.82	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	



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## 2. Package outline

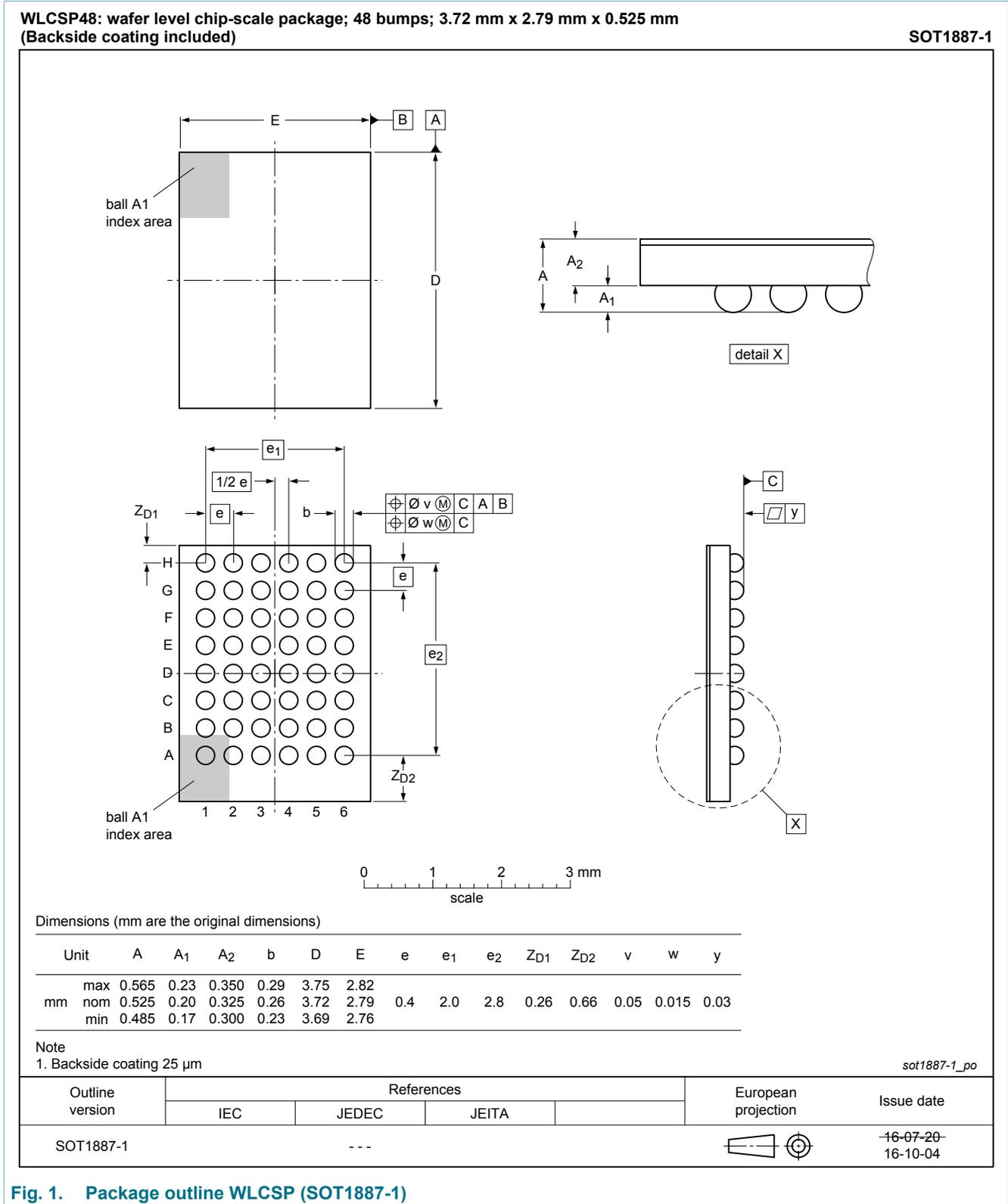


Fig. 1. Package outline WLCSP (SOT1887-1)

### 3. Legal information

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wafer level chip-scale package; 48 bumps; 3.72 mm x 2.79 mm x 0.525 mm (Backside coating included)

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